



FPF1504 / FPF1504L Advanced Load Management Switch

Features

- 1.0 V to 3.6 V Input Voltage Operating Range
- Typical $R_{DS(ON)}$:
 - 15 m Ω at $V_{IN}=3.3$ V
 - 20 m Ω at $V_{IN}=1.8$ V
 - 55 m Ω at $V_{IN}=1.0$ V
- Slew Rate Control
- Output Discharge Function
- Low <1 μ A Quiescent Current at $V_{ON}=V_{IN}$
- ESD Protected: 4000 V HBM, 2000 V CDM
- GPIO/CMOS-Compatible Enable Circuitry
- Active HIGH and active LOW versions

Applications

- Mobile Devices and Smart Phones
- Portable Media Devices
- Digital Cameras
- Advanced Notebook, UMPC, and MID
- Portable Medical Devices
- GPS and Navigation Equipment

Description

The FPF1504/FPF1504L are low- R_{DS} P-channel MOSFET load switches of the IntelliMAX™ family. Integrated slew-rate control prevents excessive inrush current from the supply rails with capacitive loads common in power applications. In addition, the FPF1504/FPF1504L feature output discharge capability.

The input voltage range operates from 1.0 V to 3.6 V to fulfill today's mobile device supply requirements. Switch control is by a logic input (ON pin) capable of interfacing directly with low-voltage CMOS control signals and GPIOs in embedded processors.

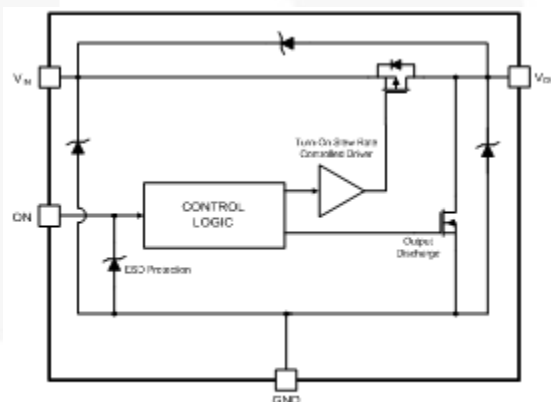


Figure 1. Block Diagram

Ordering Information

| Part Number | Top Mark | Switch (Typical) At 1.8 V _{IN} | Input Buffer | Output Discharge | ON Pin Activity | Package |
|-------------|----------|---|--------------|------------------|-----------------|--|
| FPF1504UCX | G4 | 20 m Ω | CMOS | YES | Active HIGH | 4-Ball, WLCSP, 0.5 mm Pitch |
| FPF1504BUCX | G4 | 20 m Ω | CMOS | YES | Active HIGH | 4-Ball, WLCSP with Backside Laminate, 0.5 mm Pitch |
| FPF1504LUCX | GZ | 20 m Ω | CMOS | YES | Active LOW | 4-Ball, WLCSP, 0.5 mm Pitch |

Application Diagram

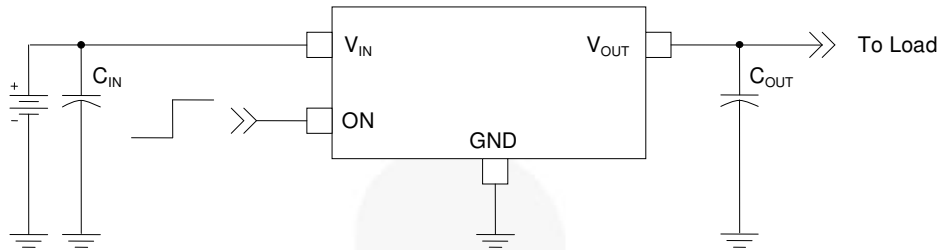


Figure 2. Typical Application

Notes:

1. $C_{IN}=1\ \mu\text{F}$, X5R, 0603, for example Murata GRM185R60J105KE26.
2. $C_{OUT}=1\ \mu\text{F}$, X5R, 0805, for example Murata GRM216R61A105KA01.

Pin Configurations

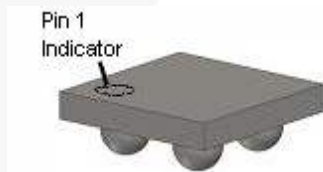


Figure 3. 1 x 1 mm WLCSP Bumps Facing Down

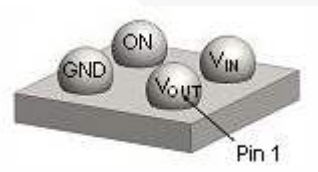


Figure 4. 1 x 1 mm WLCSP Bumps Facing Up

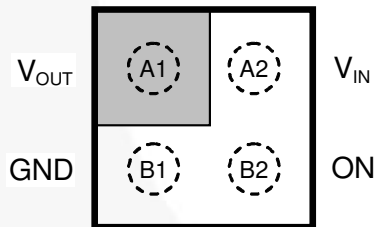


Figure 5. Pin Assignments (Top View)

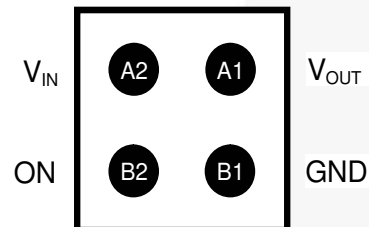


Figure 6. Pin Assignments (Bottom View)

Pin Definitions

| Pin # | Name | Description |
|-------|-----------|---|
| A1 | V_{OUT} | Switch Output |
| A2 | V_{IN} | Supply Input; Input to the Power Switch |
| B1 | GND | Ground |
| B2 | ON | ON/OFF Control |

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Min. | Max. | Unit |
|---------------|---|--------------------------------------|------|---------------------------|
| V_{IN} | V_{IN} , V_{OUT} , V_{ON} to GND | -0.3 | 4.0 | V |
| I_{SW} | Maximum Continuous Switch Current | | 1.5 | A |
| P_D | Power Dissipation at $T_A=25^\circ\text{C}$ | | 1.0 | W |
| T_{STG} | Storage Junction Temperature | -65 | +150 | $^\circ\text{C}$ |
| T_A | Operating Temperature Range | -40 | +85 | $^\circ\text{C}$ |
| Θ_{JA} | Thermal Resistance, Junction-to-Ambient | 1S2P with 1 Thermal Via | 95 | $^\circ\text{C}/\text{W}$ |
| | | 1S2P without Thermal Via | 187 | |
| ESD | Electrostatic Discharge Capability | Human Body Model, JESD22-A114 | 4 | kV |
| | | Charged Device Model, JESD22-C101 | 2 | |

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

| Symbol | Parameter | Min. | Max. | Unit |
|----------|-------------------------------|------|------|------------------|
| V_{IN} | Supply Voltage | 1.0 | 3.6 | V |
| T_A | Ambient Operating Temperature | -40 | +85 | $^\circ\text{C}$ |

Electrical Characteristics

Unless otherwise noted, $V_{IN}=1.0$ to 3.6 V, $T_A=-40$ to $+85^\circ\text{C}$; typical values are at $V_{IN}=3.3$ V and $T_A=25^\circ\text{C}$.

| Symbol | Parameter | | Conditions | Min. | Typ. | Max. | Units | |
|--------------------------------|---------------------------------------|--|---|------|------|------|---------------|-----|
| Basic Operation | | | | | | | | |
| V_{IN} | Supply Voltage | | | 1.0 | | 3.6 | V | |
| $I_{Q(OFF)}$ | Off Supply Current | FPF1504 | $V_{ON}=\text{GND}, V_{OUT}=\text{Open}$ | | 0.25 | | μA | |
| | | FPF1504L | $V_{ON}=V_{IN}, V_{OUT}=\text{Open}$ | | 0.3 | | | |
| $I_{SD(OFF)}$ | Off Switch Current | FPF1504 | $V_{ON}=\text{GND}, V_{OUT}=\text{GND}$ | | 0.25 | | | |
| | | FPF1504L | $V_{ON}=V_{IN}, V_{OUT}=\text{GND}$ | | 0.3 | | | |
| I_Q | Quiescent Current | FPF1504 | $I_{OUT}=0$ mA, $V_{IN}=3.6$ V, $V_{ON}=V_{IN}$ | | 0.08 | | | |
| | | | $I_{OUT}=0$ mA, $V_{ON}=V_{IH(MIN)}$ | | 0.75 | | | |
| | | FPF1504L | $I_{OUT}=0$ mA, $V_{IN}=3.6$ V, $V_{ON}=\text{GND}$ | | 0.08 | | | |
| | | | $I_{OUT}=0$ mA, $V_{ON}=V_{IL(MAX)}$ | | 0.95 | | | |
| R_{ON} | On Resistance | $V_{IN}=3.3$ V, $I_{OUT}=200$ mA, $T_A=25^\circ\text{C}$ | | | 15 | 30 | m Ω | |
| | | $V_{IN}=1.8$ V, $I_{OUT}=200$ mA, $T_A=25^\circ\text{C}$ | | | 20 | 40 | | |
| | | $V_{IN}=1.5$ V, $I_{OUT}=200$ mA, $T_A=25^\circ\text{C}$ | | | 30 | | | |
| | | $V_{IN}=1.0$ V, $I_{OUT}=200$ mA, $T_A=25^\circ\text{C}$ | | | 40 | 80 | | |
| | | $V_{IN}=1.8$ V, $I_{OUT}=200$ mA, $T_A=85^\circ\text{C}^{(3)}$ | | | 35 | 50 | | |
| R_{PD} | Output Discharge Pull-Down Resistance | | $V_{ON}=0$ V or V_{IN} , $I_{OUT}=-20$ mA | | 65 | 95 | Ω | |
| V_{IH} | On Input Logic High Voltage | FPF1504 | | 0.8 | | | V | |
| V_{IL} | On Input Logic Low Voltage | FPF1504 | | | | 0.3 | | |
| I_{ON} | On Input Leakage | | $V_{ON}=V_{IN}$ or GND | | | 1 | μA | |
| Dynamic Characteristics | | | | | | | | |
| t_{DON} | Turn-On Delay ⁽⁴⁾ | FPF1504 | $R_L=10$ Ω , $C_L=0.1$ μF , $V_{IN}=3.3$ V, $T_A=25^\circ\text{C}$ | | 80 | | μs | |
| t_R | V_{OUT} Rise Time ⁽⁴⁾ | FPF1504 | | | | 130 | | |
| t_{ON} | Turn-On Time ⁽⁴⁾ | FPF1504 | | | | 210 | | |
| t_{DON} | Turn-On Delay ⁽⁴⁾ | FPF1504 | $R_L=500$ Ω , $C_L=0.1$ μF , $V_{IN}=3.3$ V, $T_A=25^\circ\text{C}$ | | 70 | 100 | μs | |
| | | FPF1504L | | | | 95 | | |
| t_R | V_{OUT} Rise Time ⁽⁴⁾ | FPF1504 | | | | 110 | | 150 |
| | | FPF1504L | | | | 115 | | |
| t_{ON} | Turn-On Time ⁽⁴⁾ | FPF1504 | | | | 180 | | 250 |
| | | FPF1504L | | | | 210 | | |

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Electrical Characteristics (Continued)

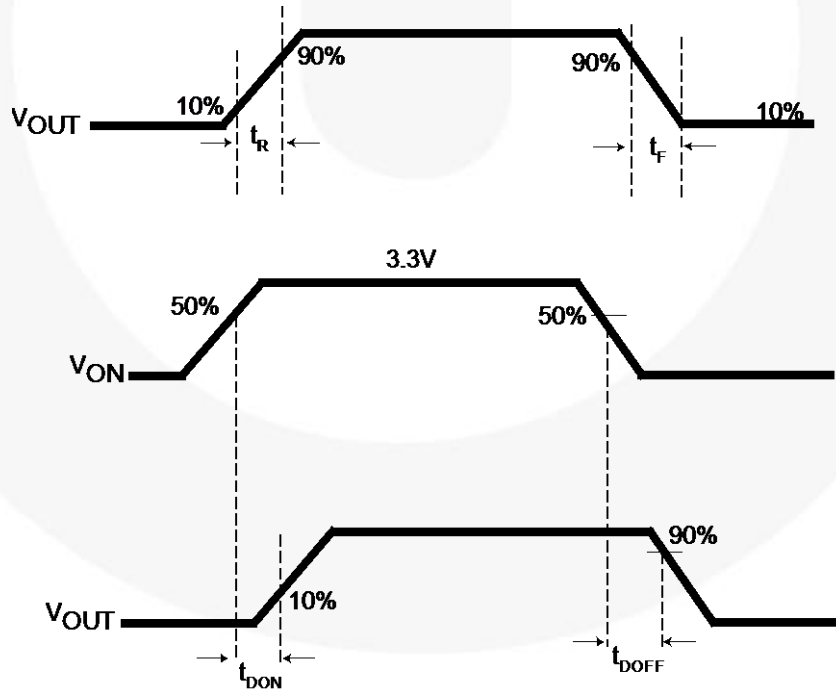
Unless otherwise noted, $V_{IN}=1.0$ to 3.6 V, $T_A=-40$ to $+85^\circ\text{C}$; typical values are at $V_{IN}=3.3$ V and $T_A=25^\circ\text{C}$.

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Units |
|--|------------------------------------|---------------------|---|----------|---------|---------------|
| Dynamic Characteristics (Continued) | | | | | | |
| t_{DOFF} | Turn-Off Delay ⁽⁴⁾ | FPF1504 | | 25 | 30 | μs |
| t_F | V_{OUT} Fall Time ⁽⁴⁾ | FPF1504 | $R_L=10\ \Omega$, $C_L=0.1\ \mu\text{F}$, $V_{IN}=3.3\ \text{V}$, $T_A=25^\circ\text{C}$ | 2 | | |
| t_{OFF} | Turn-Off Time ⁽⁴⁾ | FPF1504 | | 27 | | |
| t_{DOFF} | Turn-Off Delay ⁽⁴⁾ | FPF1504 FPF1504L | | | 25 2 | |
| t_F | V_{OUT} Fall Time ⁽⁴⁾ | FPF1504 FPF1504L | $R_L=500\ \Omega$, $C_L=0.1\ \mu\text{F}$, $V_{IN}=3.3\ \text{V}$, $T_A=25^\circ\text{C}$ | 12 14 | | |
| t_{OFF} | Turn-Off Time ⁽⁴⁾ | FPF1504 FPF1504L | | 37 16 | | |

Notes:

3. This parameter is guaranteed by design and characterization; not production tested.
4. $t_{DON}/t_{DOFF}/t_R/t_F$ are defined in Figure 7.
5. Output discharge path is enabled during off.

Timing Diagram – FPF1504



Notes:

6. $t_{ON}=t_R + t_{DON}$.
7. $t_{OFF}=t_F + t_{DOFF}$.

Figure 7. Timing Diagram for FPF1504

Typical Performance Characteristics for FPF1504

Applicable to active high version only.

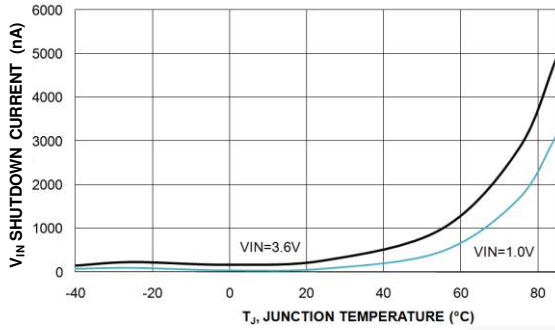


Figure 8. Shutdown Current vs. Temperature

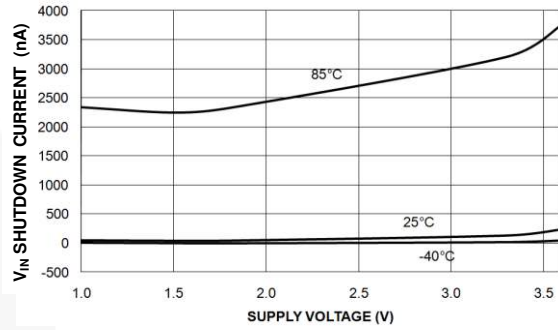


Figure 9. Shutdown Current vs. Supply Voltage

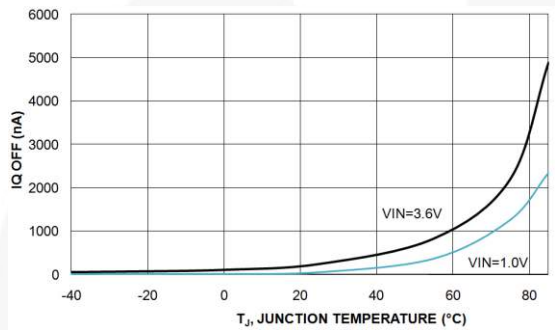


Figure 10. Off Supply Current vs. Temperature

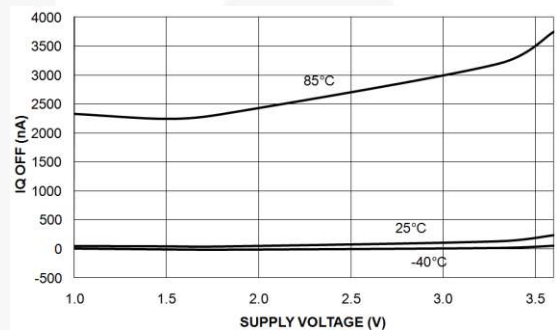


Figure 11. Off Supply Current vs. Supply Voltage

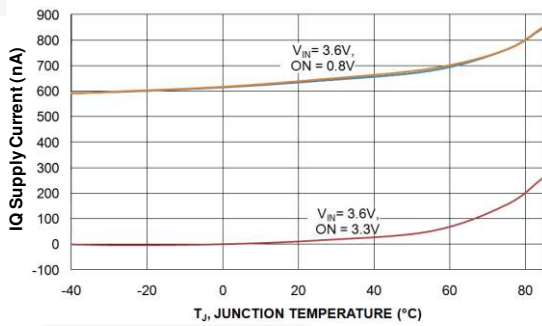


Figure 12. Quiescent Current vs. Temperature

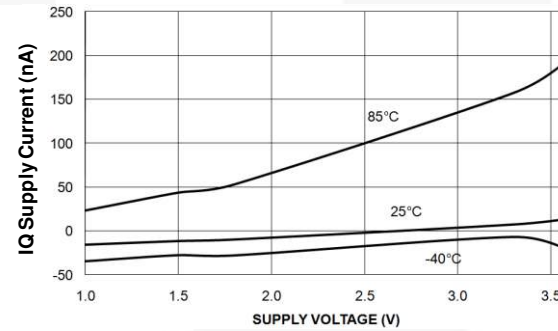


Figure 13. Quiescent Current vs. Supply Voltage ($V_{ON}=V_{IN}$)

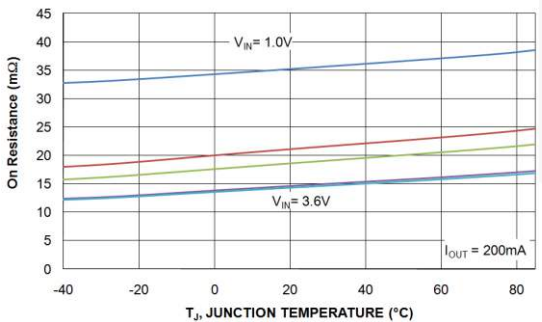


Figure 14. R_{ON} vs. Temperature

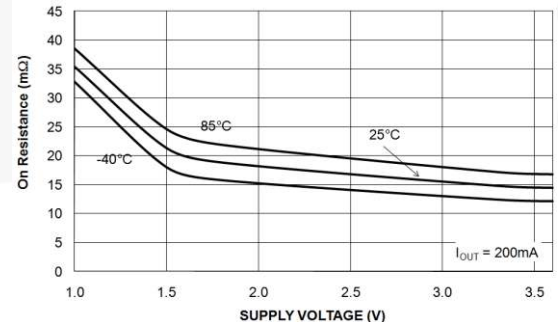


Figure 15. R_{ON} vs. Supply Voltage

Typical Performance Characteristics for FPF1504

Applicable to active high version only.

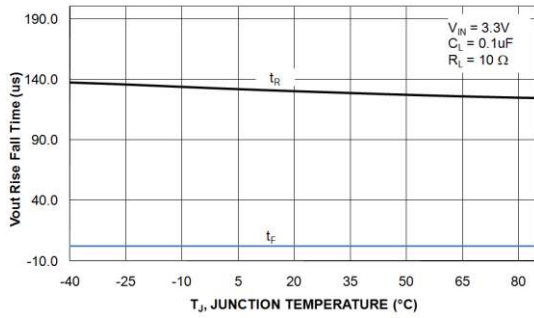


Figure 16. V_{OUT} Rise/Fall Times vs. Temperature ($R_L=10\ \Omega$)

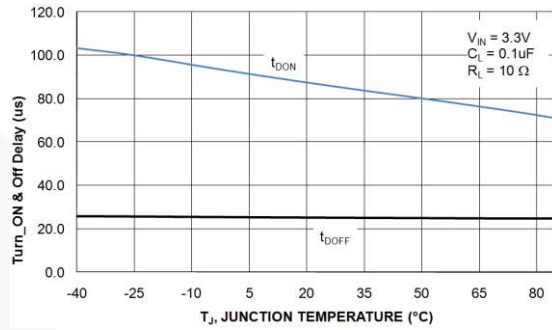


Figure 17. V_{OUT} Turn-On/Turn-Off Delays vs. Temperature ($R_L=10\ \Omega$)

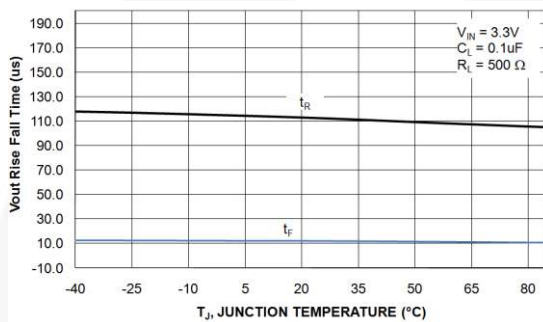


Figure 18. V_{OUT} Rise/Fall Time vs. Temperature ($R_L=500\ \Omega$)

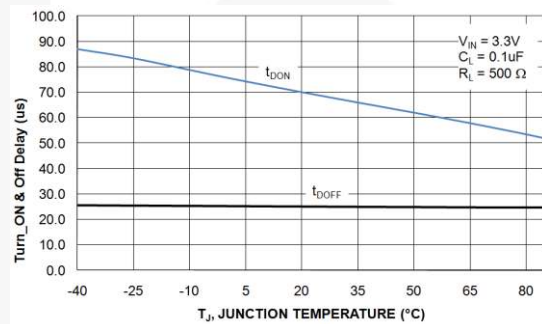


Figure 19. V_{OUT} Turn-On/Turn-Off Delays vs. Temperature ($R_L=500\ \Omega$)

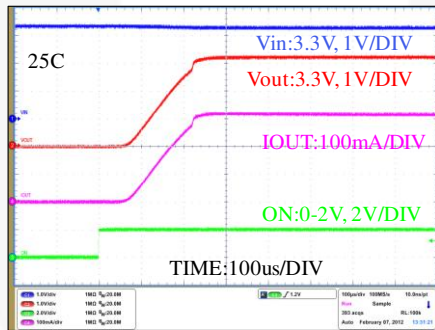


Figure 20. Turn-On Response ($V_{IN}=3.3\ V$, $C_{OUT}=0.1\ \mu F$, $R_L=10\ \Omega$)

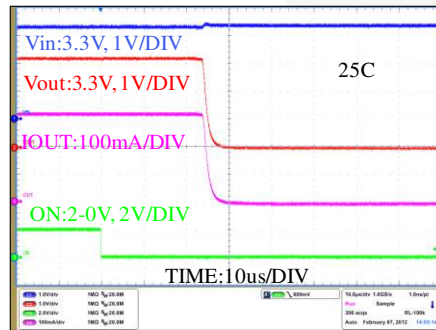


Figure 21. Turn-Off Response ($V_{IN}=3.3\ V$, $C_{OUT}=0.1\ \mu F$, $R_L=10\ \Omega$)

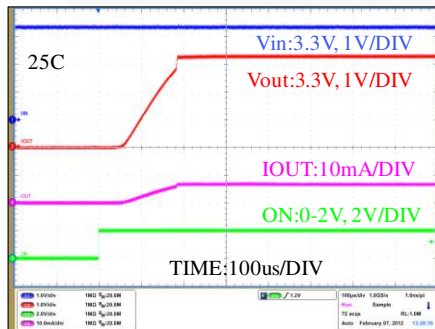


Figure 22. Turn-On Response ($V_{IN}=3.3\ V$, $C_{OUT}=0.1\ \mu F$, $R_L=500\ \Omega$)

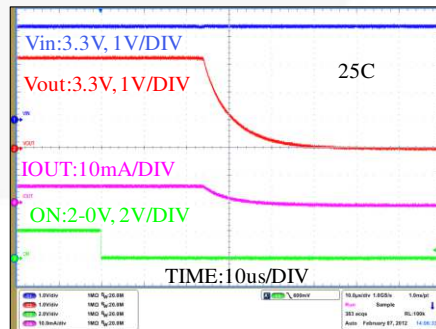


Figure 23. Turn-Off Response ($V_{IN}=3.3\ V$, $C_{OUT}=0.1\ \mu F$, $R_L=500\ \Omega$)

Application Information

Input Capacitor

IntelliMAX™ switches don't require an input capacitor. To reduce device inrush current, a 0.1 μF ceramic capacitor, C_{IN}, is recommended close to the VIN pin. A higher value of C_{IN} can be used to further reduce the voltage drop experienced as the switch is turned on into a large capacitive load.

Output Capacitor

IntelliMAX™ switches work without an output capacitor. If the applications parasitic board inductance forces V_{OUT} below GND when switching off, a 0.1 μF capacitor, C_{OUT}, should be placed between V_{OUT} and GND.

Fall Time

Device output fall time can be calculated based on RC constant of external components as follows:

$$t_F = R_L \times C_L \times 2.2 \quad (1)$$

where t_F is 90% to 10% fall time, R_L is output load, load and C_L is output capacitor.

The same equation works for a device with a pull-down output resistor, then R_L is replaced by a parallel connected pull-down and external output resistor combination, as follows:

$$t_F = \frac{R_L \times R_{PD}}{R_L + R_{PD}} \times C_L \times 2.2 \quad (2)$$

where t_F is 90% to 10% fall time, R_L is output load, R_{PD} is output pull-down resistor (65 Ω typical), and C_L is the output capacitor.

Recommended Land Pattern and Layout

For best thermal performance and minimal inductance and parasitic effects, it is recommended to keep input and output traces short and the capacitors as close to

the device as possible. Below is a recommended layout for this device to achieve optimum performance.

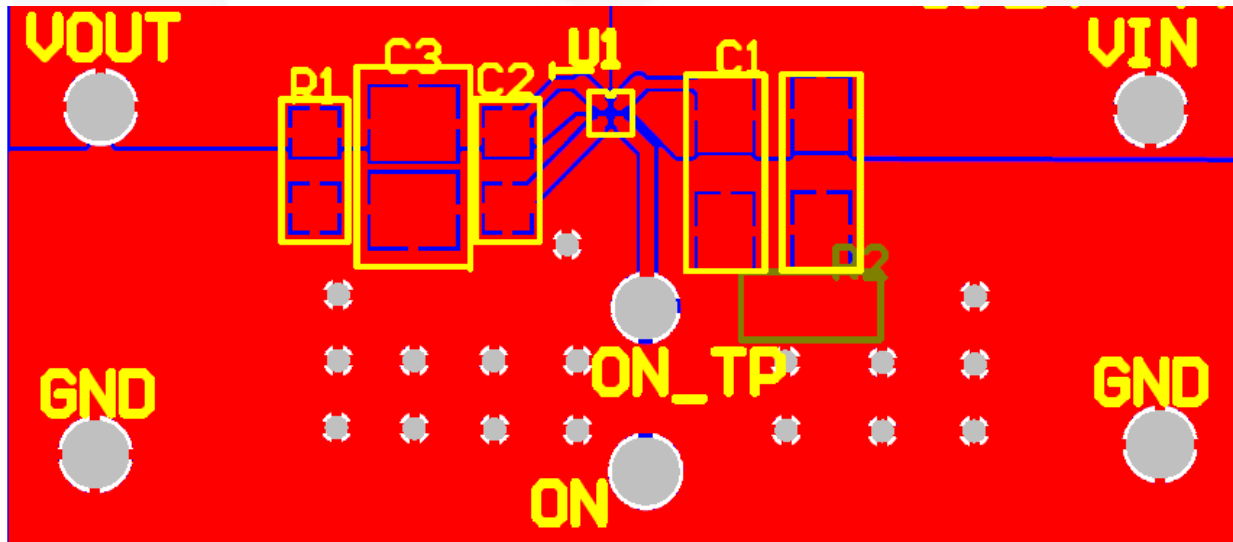
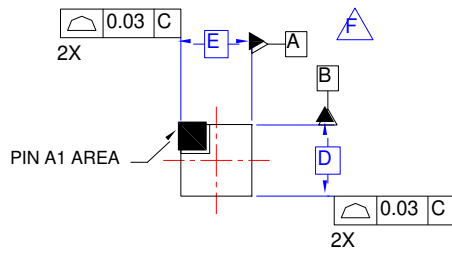
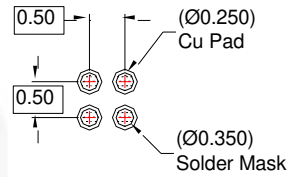


Figure 24. Recommended Land Pattern and Layout

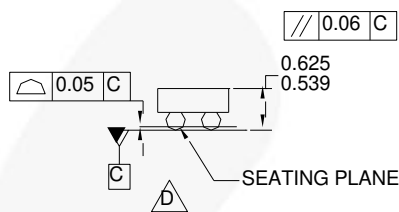
Physical Dimensions



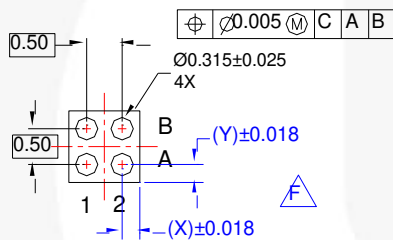
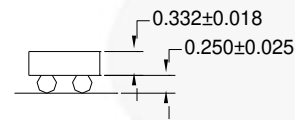
TOP VIEW



RECOMMENDED LAND PATTERN
(NSMD PAD TYPE)



SIDE VIEWS



BOTTOM VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE NOMINAL HEIGHT IS 582 MICRONS ±43 MICRONS (539-625 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- G. DRAWING FILENAME: MKT-UC004ABrev2.

Figure 25. 4-Ball, 1.0 x 1.0 mm Wafer-Level Chip Scale (WLCSP) Packaging

Product-Specific Dimensions

| Product | D | E | X | Y |
|-------------|---------------|---------------|----------|----------|
| FPF1504UCX | 960 μm ±30 μm | 960 μm ±30 μm | 0.230 mm | 0.230 mm |
| FPF1504BUCX | | | | |
| FPF1504LUCX | | | | |



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PRODUCT STATUS DEFINITIONS

Definition of Terms

| Datasheet Identification | Product Status | Definition |
|--------------------------|-----------------------|---|
| Advance Information | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice. |
| Preliminary | First Production | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
| No Identification Needed | Full Production | Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design. |
| Obsolete | Not In Production | Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only. |

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